



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752 Distribute</b>	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	<b>Material Info Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2016-02-17</b>
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	<b>LAURENT TOSI</b>	<b>Representative Title</b>	<b>MMS MD CHAMPION</b>
<b>Representative Phone *</b>	33 442 685 795	<b>Representative Email *</b>	<a href="mailto:laurent.tosi@st.com">laurent.tosi@st.com</a>
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/online_tech_support.html">http://www.st.com/web/en/support/online_tech_support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M95M02-DRMN6TP	PG07*95M21KA	A	3068	2016-02-17
	Amount	UoM	Unit type	ST ECOPACK Grade
	80.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SON	NAC	8	L bend	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	PG07*95M21KA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	4.982	mg	supplier	die	Silicon (Si)	7440-21-3		4.793	mg	962063	59913
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	3613	225
Die				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	201	13
Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	602	38
Die				supplier	metallization	Tungsten (W)	7440-33-7		0.003	mg	602	38
Die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.012	mg	2409	150
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.152	mg	30510	1900
Lead-frame	Other inorganic materials	30.315	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.420	mg	970503	367756
Lead-frame				supplier	alloy	Iron (Fe)	7439-89-6		0.708	mg	23364	8853
Lead-frame				supplier	alloy	Zinc (Zn)	7440-66-6		0.036	mg	1195	453
Lead-frame				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.025	mg	837	317
Lead-frame				supplier	coating	Nickel (Ni)	7440-02-0		0.114	mg	3761	1425
Lead-frame				supplier	coating	Palladium (Pd)	7440-05-3		0.007	mg	241	91
Lead-frame				supplier	coating	Gold (Au)	7440-57-5		0.003	mg	100	38
Die Attach	Other inorganic materials	2.460	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		2.214	mg	900000	27675
Die Attach				supplier	glue or soft solder	acrylate	na		0.148	mg	60000	1845
Die Attach				supplier	glue or soft solder	Methacrylate	na		0.093	mg	38000	1169
Die Attach				supplier	glue or soft solder	acrylate	na		0.005	mg	2000	62
Wires	Other inorganic materials	0.062	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.062	mg	1000000	776
Encapsulation	Other inorganic materials	42.180	mg	supplier	Moulding Compound	Epoxy Resin	na		3.178	mg	75335	39720
Encapsulation				supplier	Moulding Compound	Phenol Resin	na		2.118	mg	50223	26480
Encapsulation				supplier	Moulding Compound	Silica, vitreous	60676-86-0		36.503	mg	865402	456283
Encapsulation				supplier	Moulding Compound	Carbon-black	1333-86-4		0.212	mg	5022	2648
Encapsulation				supplier	Moulding Compound	Bismuth (Bi)	7440-69-9		0.169	mg	4018	2118
Finishing	Other inorganic materials	0.001	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.001	mg	916800	14
Finishing				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	58700	1
Finishing				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	24500	0